1. (normative)
Assembly Summary Table - DRD
	1. DRD identification
		1. Requirement identification and source document

This DRD is called from ECSS-Q-ST-70-61, requirement 13.1.7d.

* + 1. Purpose and objective

The purpose of the assembly summary table is to consolidate the approval status of the boundary conditions for the verification activity.

An assembly summary table is issued for each assembly process.

* 1. Expected response
		1. Scope and content

The assembly summary table shall include the following data:

Assembly processes

PID reference with issue

Solder type for machine reflow and for hand assembly

Conformal coating

Substrate type

Component data.

1. An example of a component type preparation and mounting configuration table is given in Figure D-1.
	* 1. Special remarks

None.

| Component family  | Package | Manufacturer | Package dimensions  | Bonding material (under component) | Staking material (edge or corner) | Termination material | Lead finish | Pitch(mm) | Nominal Termination thickness (mm)/ Nominal width | In-House degolding / pretinning | In-house lead forming Yes/No/NA | Artificial stand-off Yes/No | Final report |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| Ceramic chip | C0603 Type I |  | Length, width | NA | NA |  | Sn/Pb | NA | NA | No | N/A | No |  |
| Ceramic | C0603 Type II |  |  |  |  |  |  |  |  |  | N/A |  |  |
| Ceramic resistor | R0805 |  |  | NA | NA |  | Sn/Pb | NA | NA | No | N/A | No |  |
| Diode | D5-B |  |  |  |  |  |  |  |  |  | N/A |  |  |
| Tantalum capacitors |  |  |  |  |  |  |  |  |  |  |  |  |  |
| IC | FP10 Bottom brazed |  |  | yes | One the side | Alloy42 | Gold | 1,27 | 0,25 | yes | yes | NA |  |
| CQFP | CQFP196 top brazed |  |  |  |  | Kovar |  |  |  |  | No |  |  |

: Example of component type preparation and mounting configuration